

7 interposer to the package, the interposer further having a second plurality of contacts
8 spaced at said pitch to couple the interposer to the circuit board.

1 10. (Amended) An interposer comprising:

2 a circuit board substrate having a first surface and a second surface;
3 a first plurality of conductive contacts spaced at a pitch on the first surface to be
4 fixedly coupled to an electronic component package;
5 a second plurality of conductive contacts spaced at said pitch on the second
6 surface to be fixedly coupled to a circuit board; and
7 a plurality of conductive paths, each separately connecting one of the first
8 plurality of conductive contacts with one of the second plurality of conductive contacts.

1 18. (Amended) An electronic apparatus comprising:

2 a die having a plurality of electronic circuits formed thereon;
3 a package substrate having a first surface coupled to the die and a second
4 surface;
5 a circuit board; and
6 an interposer coupled between the second surface of the package substrate and
7 the circuit board, the interposer comprising
8 a circuit board substrate having a first surface and a second surface,
9 a first plurality of conductive contacts disposed at a pitch on the first
10 surface of the circuit board substrate, to be fixedly coupled to an electronic component
11 package,

12 a second plurality of conductive contacts disposed at said pitch on the
13 second surface of the circuit board substrate, to be coupled to a circuit board, and
14 a plurality of conductive paths, each separately connecting one of the first
15 plurality of conductive contacts with one of the second plurality of conductive contacts.

Q⁴ 1 23. (Amended) A method of coupling an electronic circuit package to a circuit board,
2 the method comprising:
3 fixedly coupling a plurality of electrical contacts on a first surface of an
4 interposer to the electronic circuit package, the interposer formed from a circuit board
5 substrate having the first surface, a second surface, and a plurality of conductive paths
6 from the first surface to the second surface; and
7 fixedly coupling a plurality of electrical contacts on the second surface to the
8 circuit board, the interposer such that the first plurality of electrical contacts and the
9 second plurality of electrical contacts are spaced at an equal pitch.

Please add the following new claims:

Q⁵ 1 50. (New) An apparatus as recited in claim 1, wherein the interposer is to be fixedly
2 coupled to the circuit board.

1 51. (New) An interposer as recited in claim 26, wherein the first plurality of conductive
2 contact pads and the second plurality of conductive contact pads are spaced at an equal
3 pitch.

REMARKS

Please enter the above amendments prior to examining the present application.

Claims 1, 10, 18 and 23 have been amended. No new matter has been added.

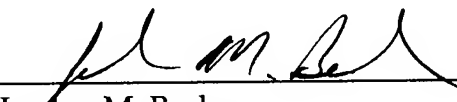
The amendments are made only to place the claims in a better form and are not made in response to any requirement of patentability.

Applicants respectfully submit that the amendments to the claims are fully supported by the description in the application as filed, and do not constitute new matter, even though the exact wording of the added claim language might not be found in the application as filed. For example, the claim language of the first plurality of contacts and the second plurality of contacts both being spaced at the same pitch is at least implicitly supported by the illustrations in at least Figures 5 through 10. The claim language of "fixedly coupling" the interposer to the package is supported at least by the description found in Figure 13 (e.g., block 1303) and in paragraph "[0034]" of Applicants' specification as filed.

If any additional fee is required, please charge Deposit Account No. 02-2666.

Respectfully submitted,
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

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Jordan M. Becker
Reg. No. 39,602

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300